

FIG. 2

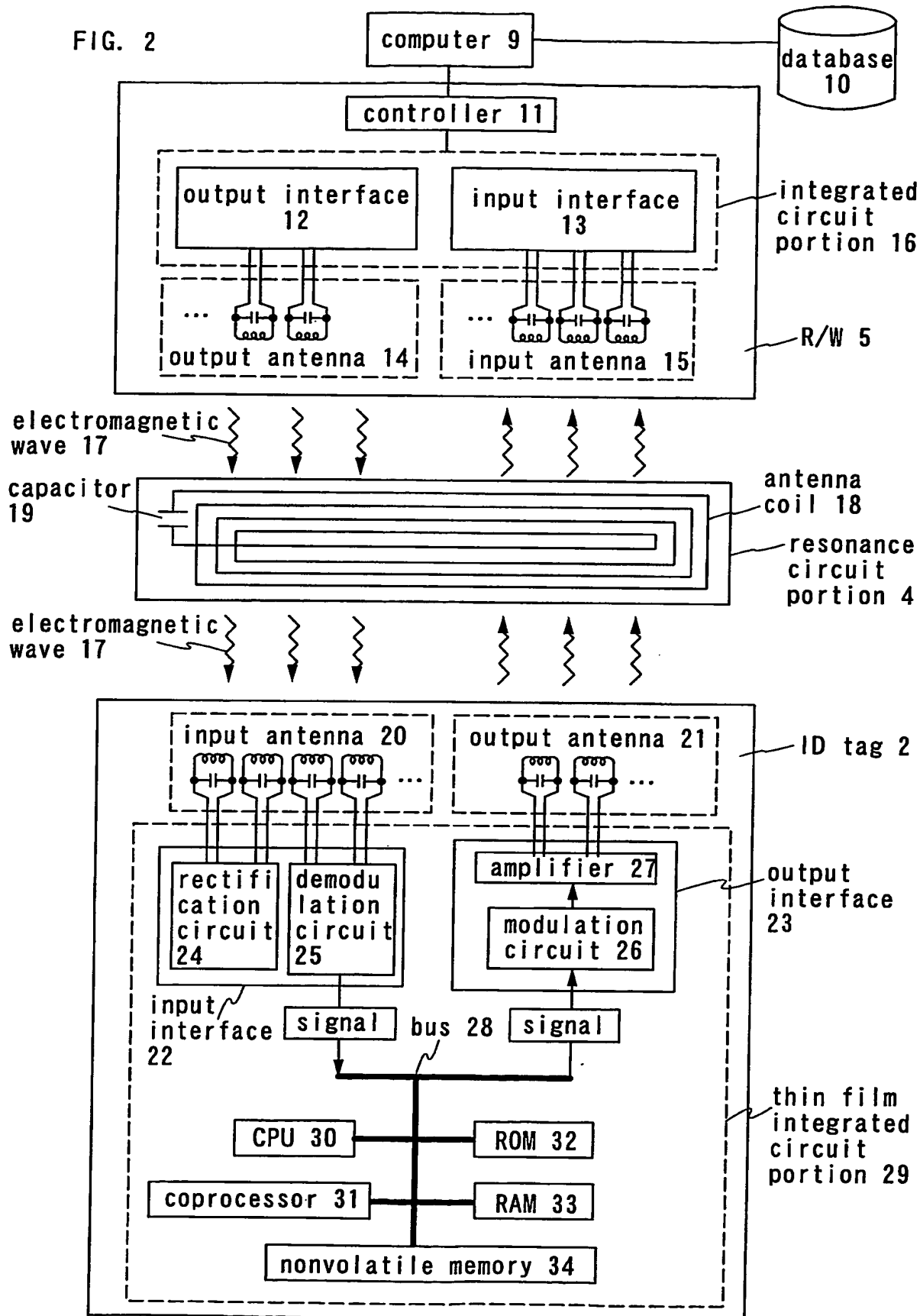


FIG. 3

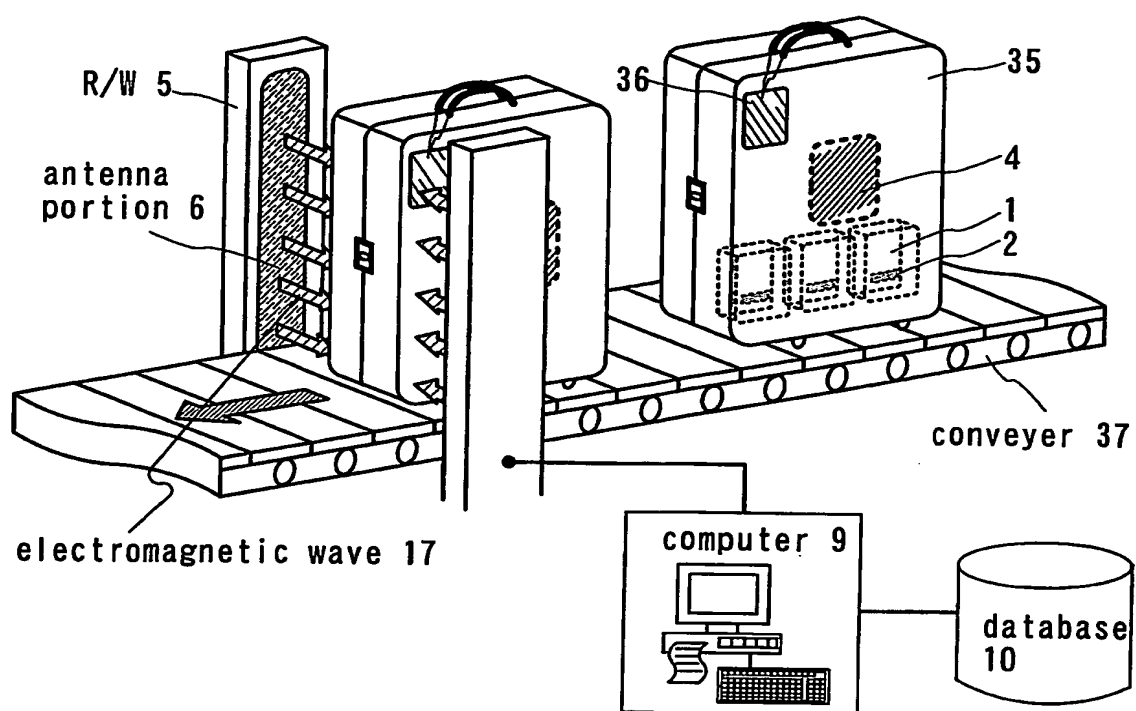
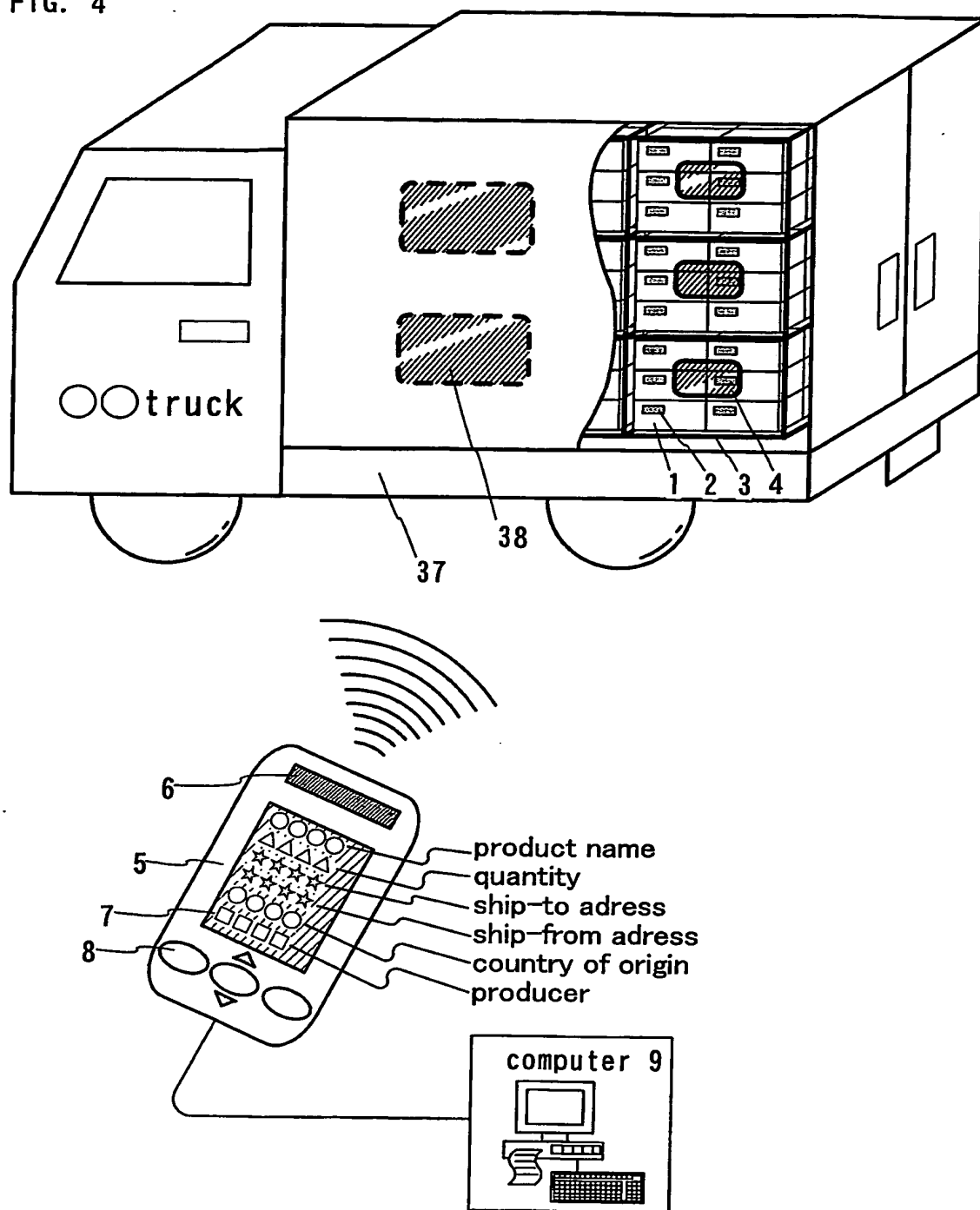


FIG. 4



5/14

FIG. 5A

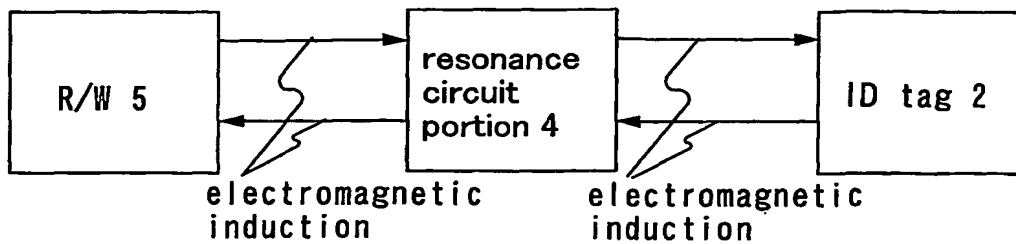


FIG. 5B

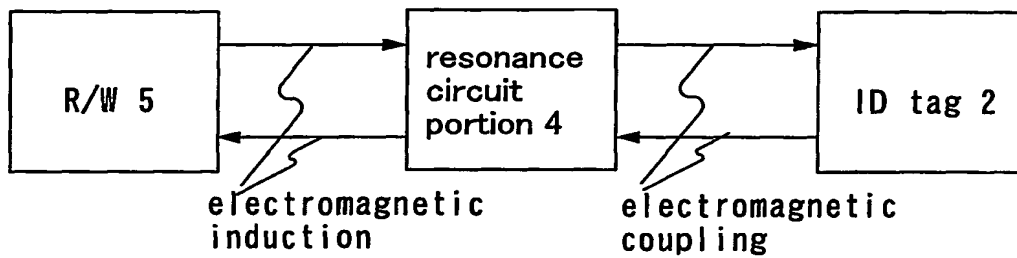
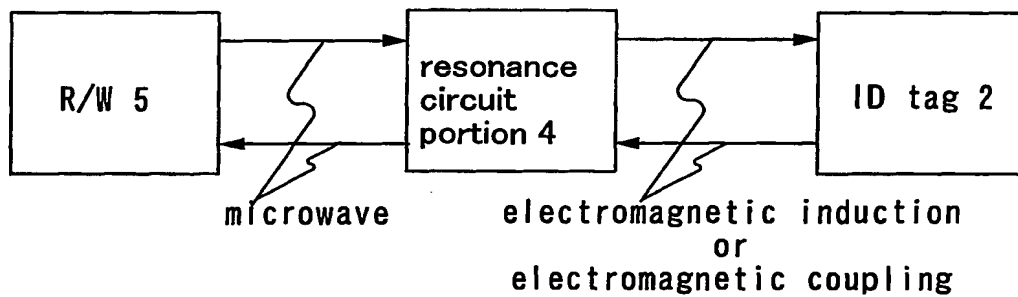


FIG. 5C



6/14

FIG. 6

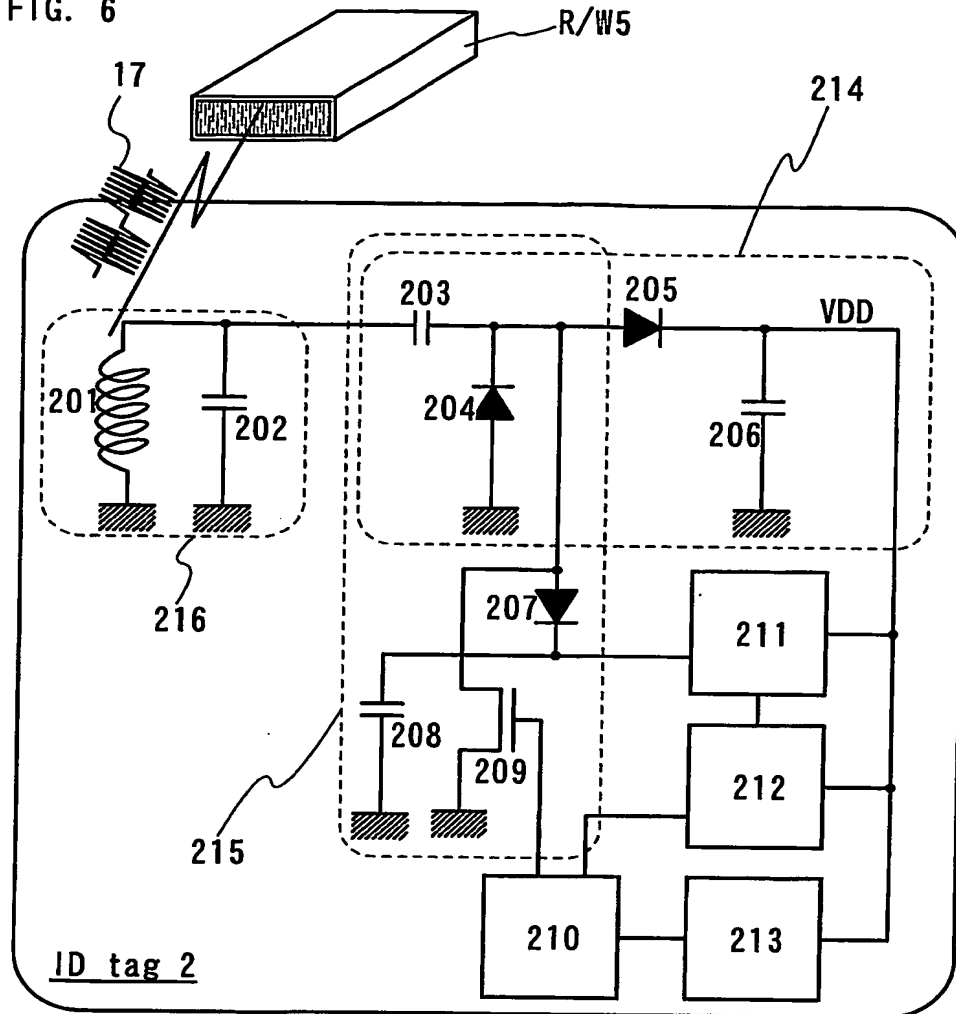


FIG. 7A forming separation layer and protective film

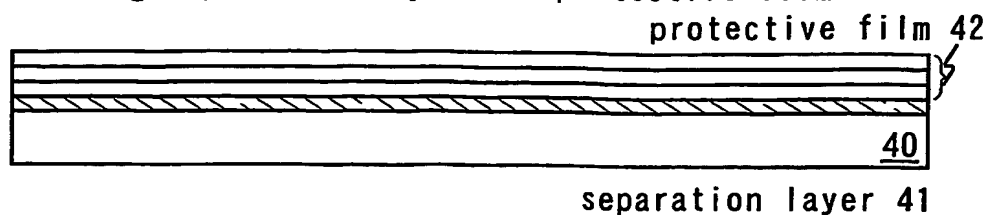


FIG. 7B forming semiconductor film and gate insulating film

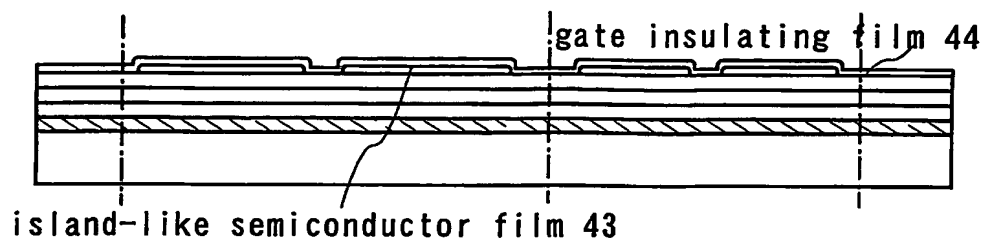


FIG. 7C forming gate electrode

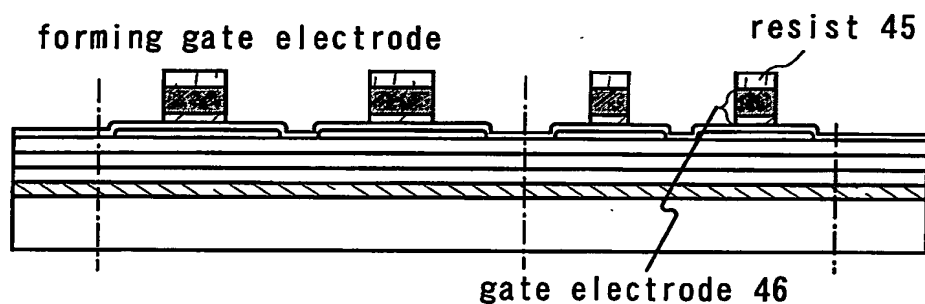


FIG. 7D forming n-type low concentration impurity region

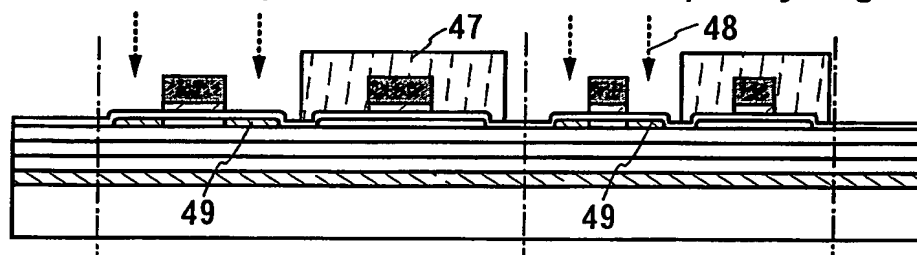


FIG. 7E forming p-type high concentration impurity region

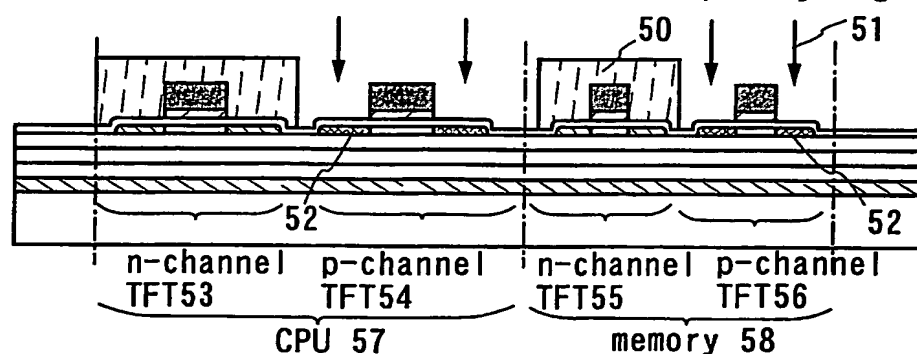


FIG. 8F forming insulatin film

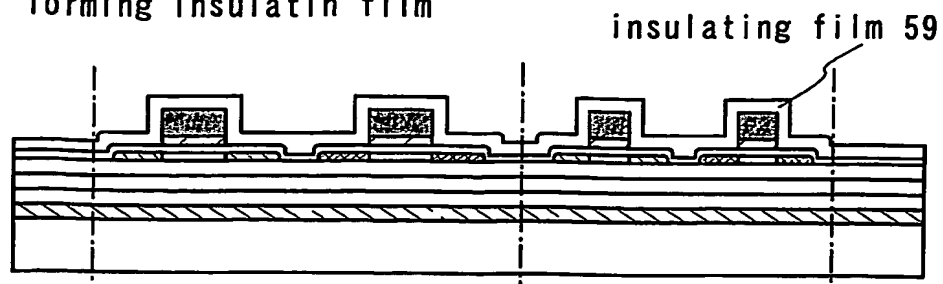


FIG. 8G etchback (forming sidewall)

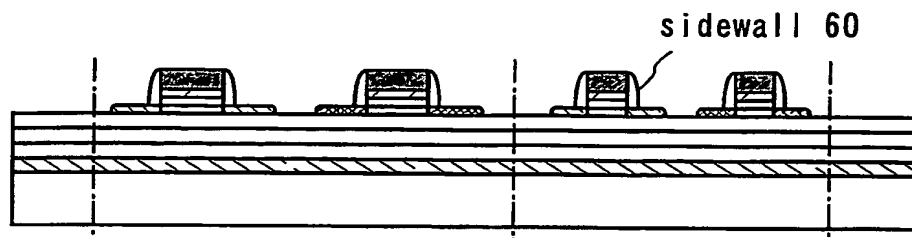


FIG. 8H forming n-type high concentration impurity region

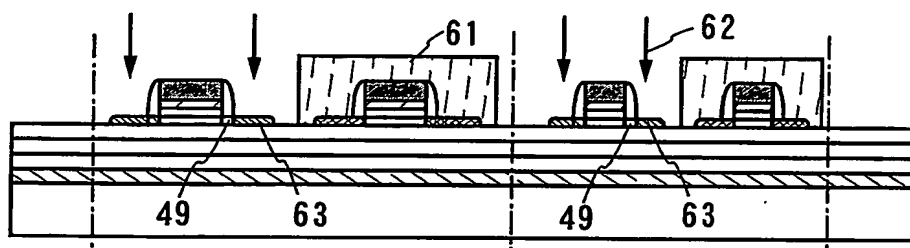


FIG. 81 forming interlayer, protective film and wiring

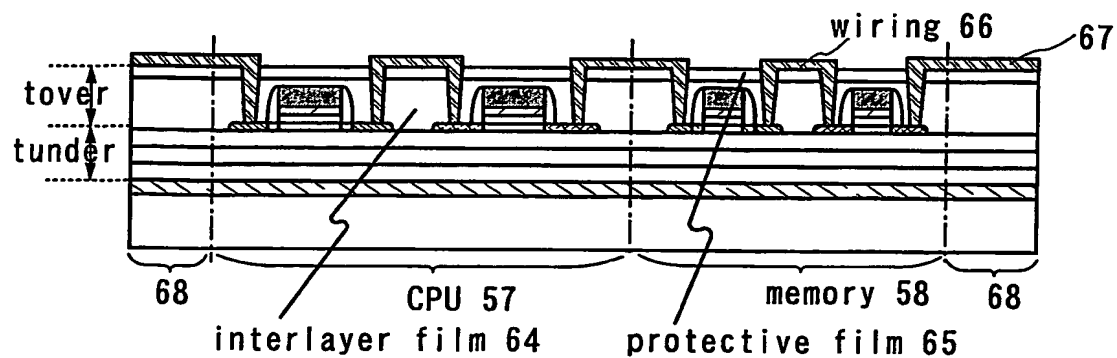


FIG. 9J forming thin film integrated circuit device

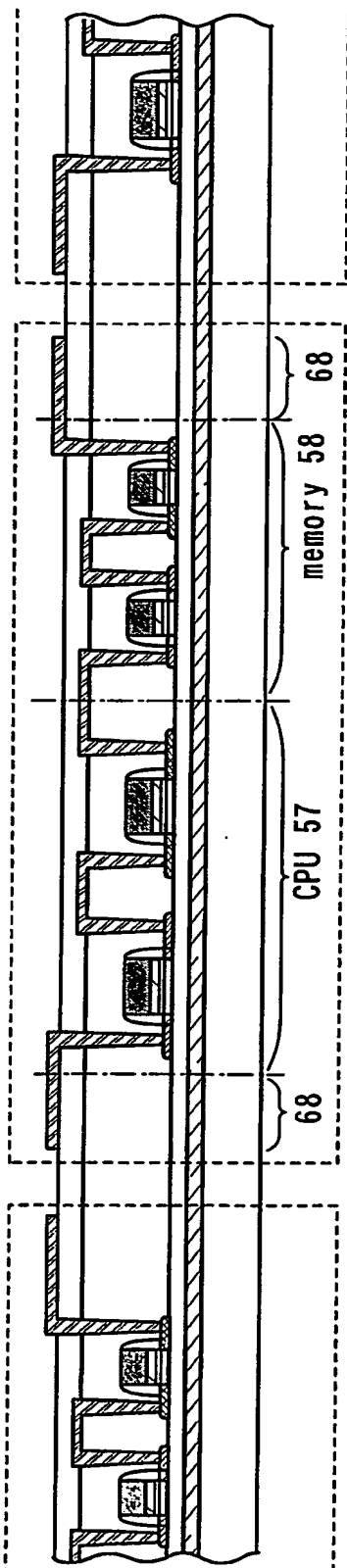


FIG. 9K forming groove 70 thin film integrated circuit portion 69

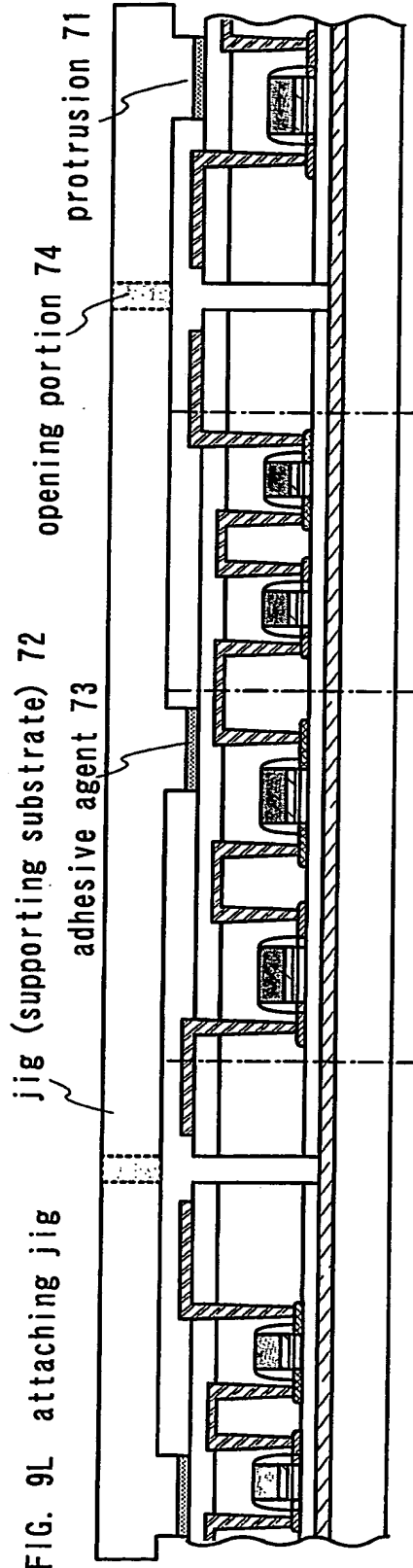
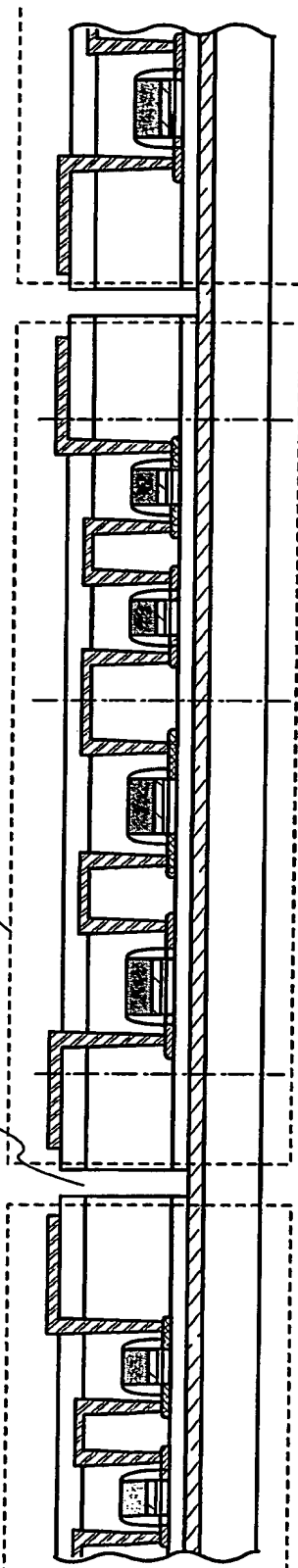


FIG. 10M introducing halogen fluoride

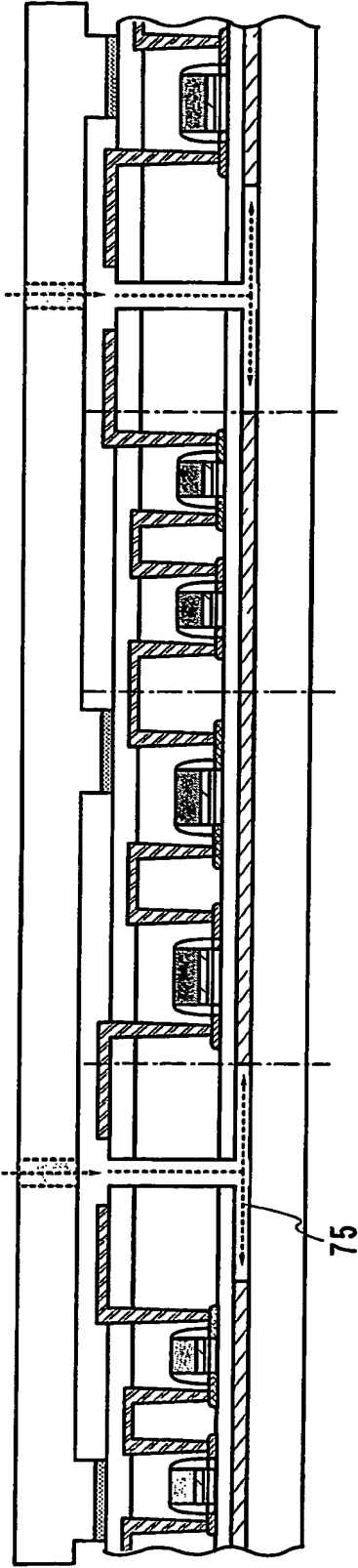


FIG. 10N separating substrate

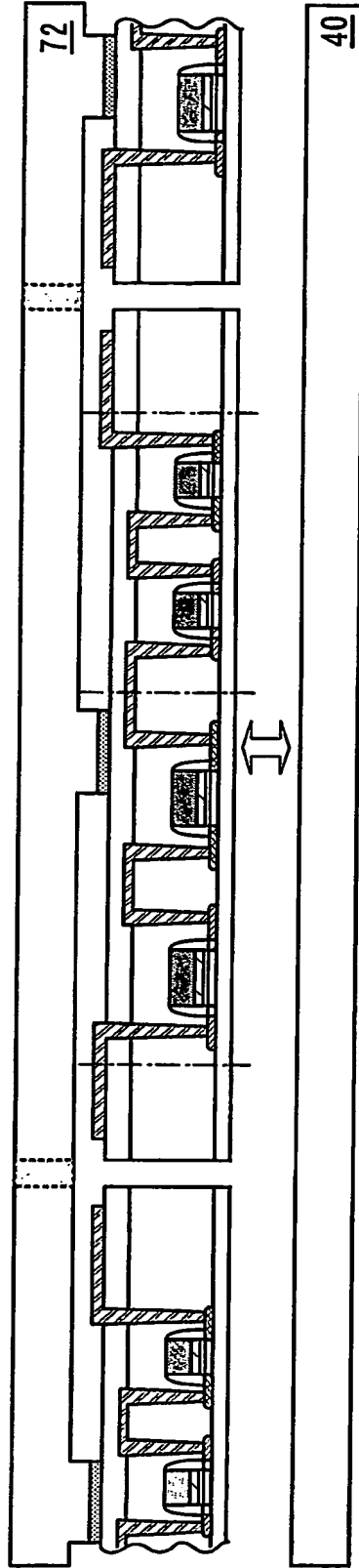
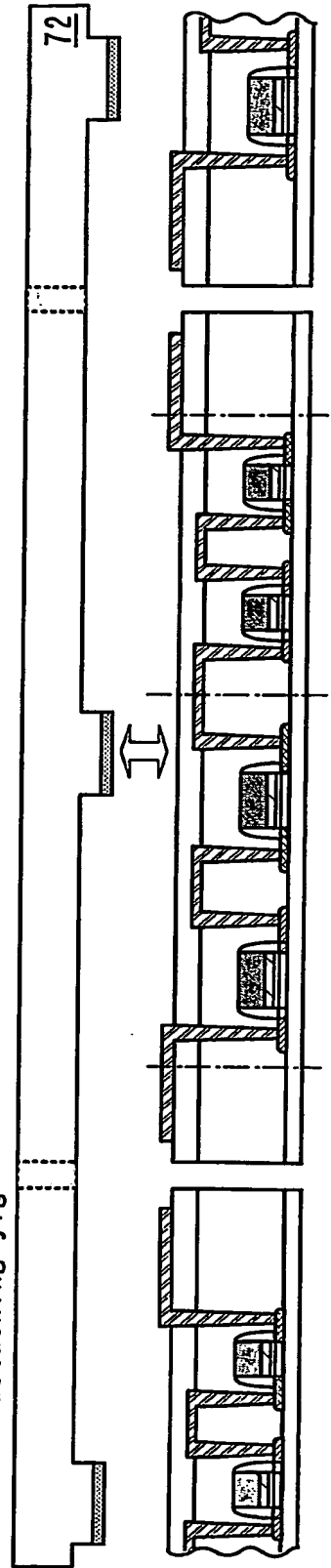


FIG. 100 detaching jig



11/14

FIG. 11A

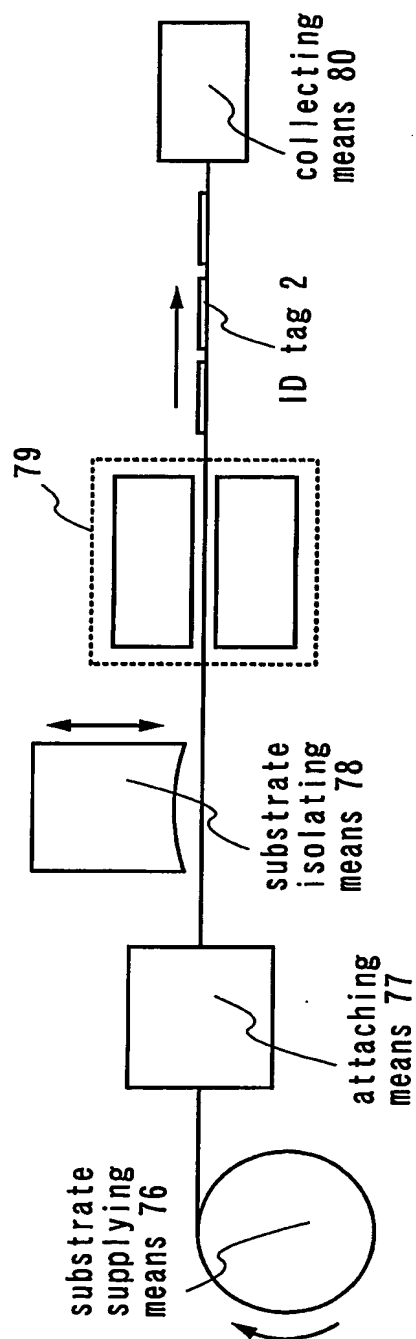
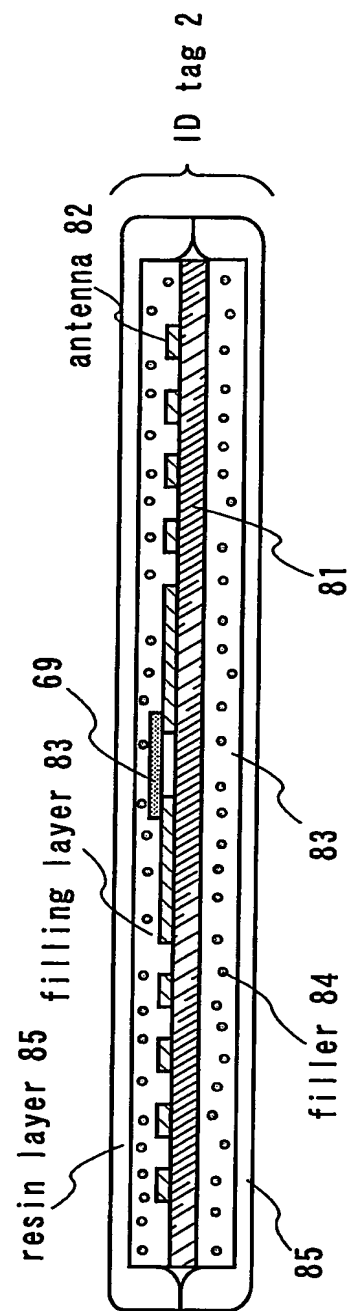


FIG. 11B magnified drawing of IDtag as a completed article



12/14

FIG. 12

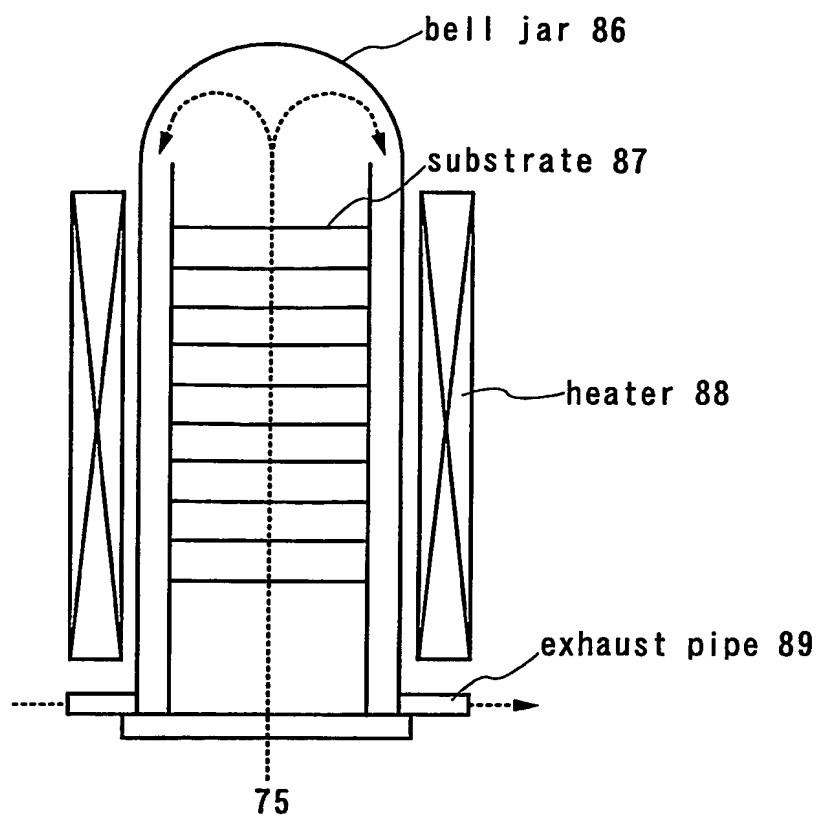


FIG. 13A transferring and aligning substrate

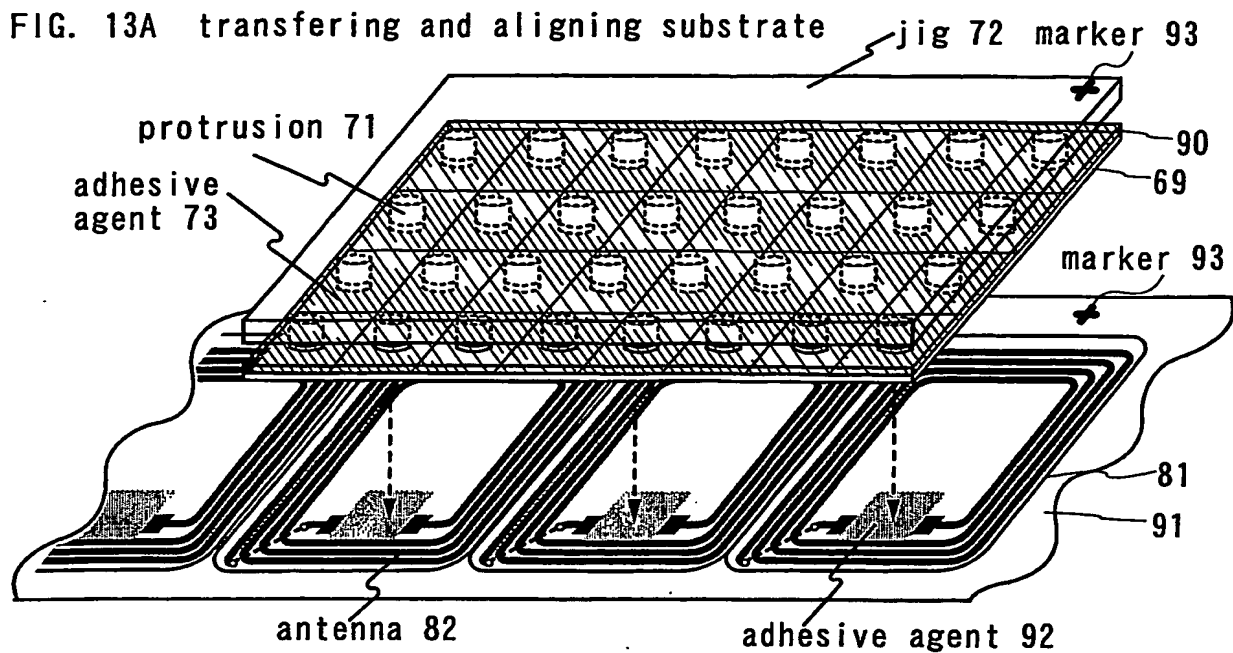


FIG. 13B attaching thin film integrated circuit portion

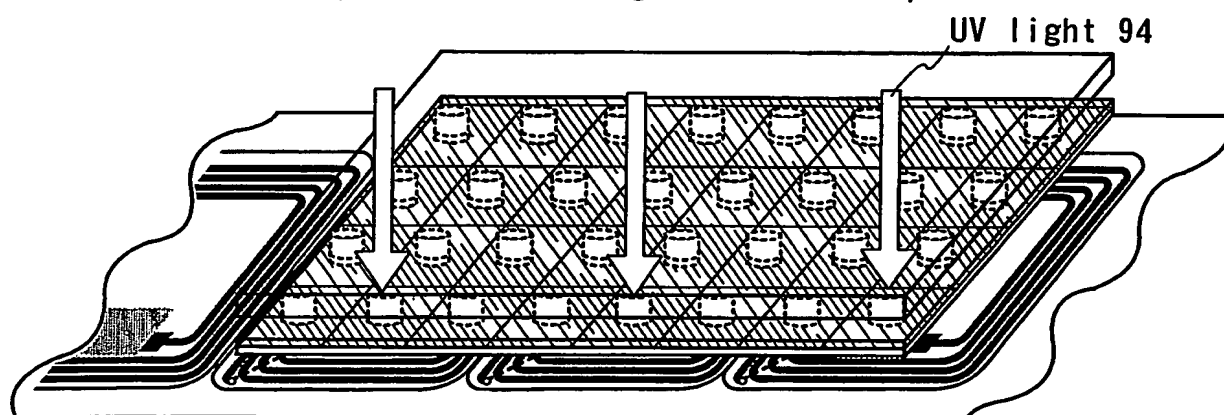
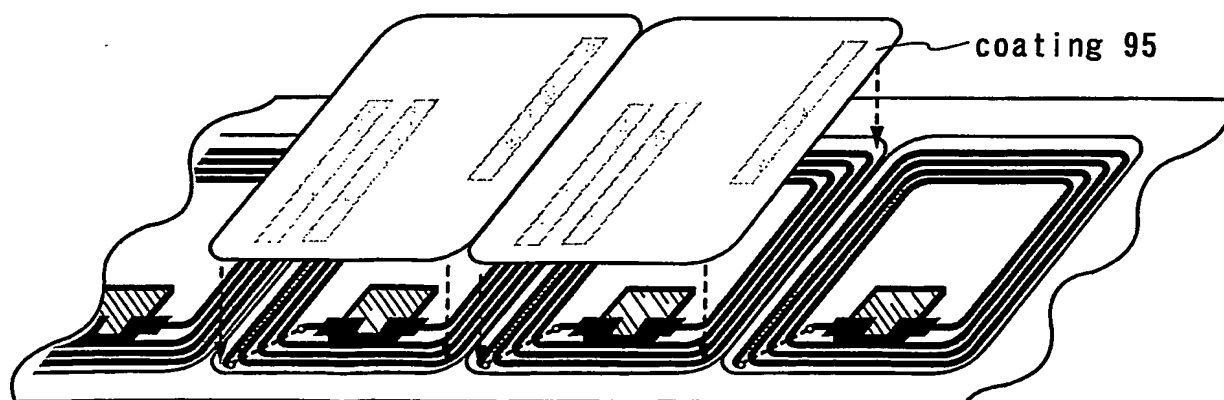


FIG. 13C covering by coating



EXPLANATION OF REFERENCE

1. product, 2. ID tag, 3. package body, 4. resonance circuit portion, 5. R/W, 6. antenna portion, 7. display portion, 8. operation key, 9. computer, 10. database, 11. controller, 12. output interface, 13. input interface, 14. output antenna, 15. input antenna, 16. integrated circuit portion, 17. electromagnetic wave, 18. antenna coil, 19. capacitor, 20. input antenna, 21. output antenna, 22. input interface, 23. output interface, 24. rectification circuit, 25. demodulation circuit, 26. modulation circuit, 27. amplifier, 28. bus, 29. thin film integrated circuit portion, 30. CPU, 31. coprocessor, 32. ROM, 33. RAM, 34. nonvolatile memory, 35. suitcase, 36. price tag, 37. conveyer, 38. transportation vehicle, 39. resonance circuit portion, 40. substrate, 41. separation layer, 42. protective film, 43. island-like semiconductor film, 44. gate insulating film, 45. resist, 46. gate electrode, 47. resist, 48. impurity element, 49. low concentration impurity region, 50. resist, 51. impurity element, 52. p-type high concentration impurity region, 53. n-channel TFT, 54. p-channel TFT, 55. n-channel TFT, 56. p-channel TFT, 57. CPU, 58. memory, 59. insulating film, 60. sidewall, 61. resist, 62. impurity element, 63. n-type high concentration impurity region, 64. interlayer film, 65. protective film, 66. wiring, 67. connection wiring, 68. antenna connection portion, 69. thin film integrated circuit portion, 70. groove, 71. protrusion, 72. jig, 73. adhesive agent, 74. opening portion, 75. halogen fluoride gas, 76. substrate supplying means, 77. attaching means, 78. substrate isolating means, 79. laminating device, 80. collecting means, 81. inlet substrate, 82. antenna, 83. filling layer, 84. filler, 85. laminate resin layer, 86. bell jar, 87. substrate, 88. heater, 89. exhaust pipe, 90. protective film, 91. stage, 92. adhesive agent, 93. marker, 94. UV light, 95. coating, 201. antenna wiring, 202. antenna capacitor, 203. first capacitor means, 204. first diode, 205. second diode, 206. second capacitor means, 207. third diode, 208. third capacitor means, 209. switching element, 210. logic circuit, 211. amplifier, 212. clock generation circuit-decoder, 213. memory, 214. power supply circuit, 215. input-output circuit, 216. antenna circuit,